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_	Applicant Initi	ated Interview	Request Fo	rm		
Application No.: 10/552,	681	First Nam	First Named Applicant: Roche Diagnostics Operations, In			
Examiner: Joel G. Horning Art Unit: 1792 Status of Application: Pending						
Tentative Participants: (1) Attorney Timothy N. (3)	Γhomas		niner Joel G. Horning			
Proposed Date of Intervi	roposed Time: 1:30					
Type of Interview Reque	sted:		ı			
(1) Video Conference						
Exhibit To Be Shown or If yes, provide brief desc		YES	V NO	1		
Issues To Be Discussed						
Issues (Rej., Obj., etc) (1) 12	Claims/ Fig. #s	Prior Art Wojnarowski et al US 5.302.547	Discussed	Agreed	Not Agreed	
(2)						
(3)		-				
(4)		1				
Continuation Shee	t Attached				·	
Brief Description of Argument to be Presented: Please See Attached Sheet						
An interview was conduct NOTE: This form should (see MPEP § 713.01). This application will not interview. Therefore, appropriate the soon as possible. Applicant/Applicant's Timothy N. Thomas Typed/Printed Name of 35714 Registration Num	the completed by applicant is advised to find the Representative Signat Applicant or Representative Signates	plicant and submitted to because of applicant's ile a statement of the subure	s failure to submit a	written reco view (37 CF	rd of this	

This collection of information is required by 37 CFR 1.133. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 21 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Re:

United States Patent Application No. 10/552,681

Filing Date:

February 28, 2007

Title:

METHOD FOR PRODUCING MULTIPLE LAYER

SYSTEMS

Inventor(s):

Meier, Bhullar

Our Ref.:

007404-000740

Applicants' claim 12 includes the limitation that an intermediate, "sacrificial" layer is used to selectively remove an adjacent non-conductive or metallic layer. In particular, a sacrificial layer (such as an organic polymer layer) is deposited adjacent a dielectric layer and photon energy is introduced into the sacrificial layer to ablate the sacrificial layer and thereby to remove either the non-conductive layer above or the metallic layer below. Applicants believe that that feature is neither taught nor suggested by Wojnarowski.

The pending Office Action appears to contend that Wojnarowski discloses applying energy to a sacrificial layer to remove either a non-conductive layer above or a metallic layer below. In particular, the Office Action appears to contend that Wojnarowski provides a non-conductive layer 76 adjacent an intermediate sacrificial (bi)layer 18/20, and uses laser energy to ablate the intermediate (bi)layer 18/20, thus removing the non-conductive layer 76.

Applicants' review of the Wojnarowski '547 patent suggests that the Wojnarowski non-conductive layer is removed by ablating it directly, and not by the ablation of an adjacent "sacrificial" layer. Wojnarowski discloses a non-conductive layer that overlies a dielectric layer, and Wojnarowski teaches that "[t]he nitride film is removed at the same time and in the same area during the laser ablation of second dielectric layer 20." Wojnarowski '547 at col. 7, lines 60-63. This appears to disclose using a laser to ablate both layers directly, rather than ablating only the intermediate/sacrificial layer and causing the non-conductive layer to be removed as a consequence of that ablation of the dielectric layer.

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